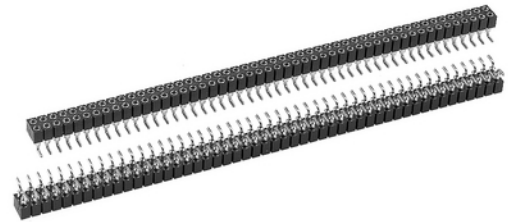


SMT-Präzisions-Buchsenleisten RM 2,00mm, stehend/liegend, 1-/2-reihig SMT Precision Female Headers, 2.00mm Pitch, Vertical/Horizontal, 1/2 Rows

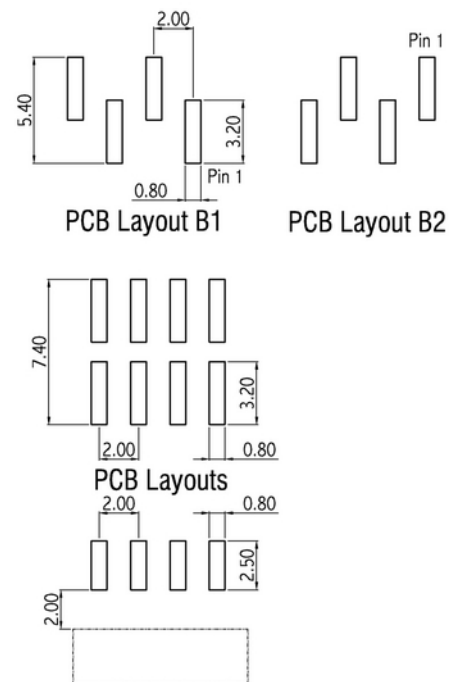
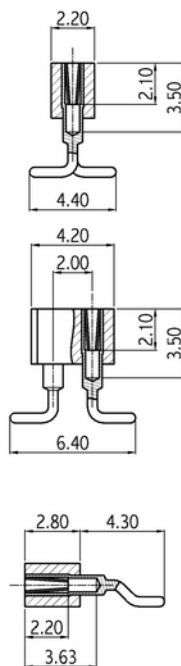
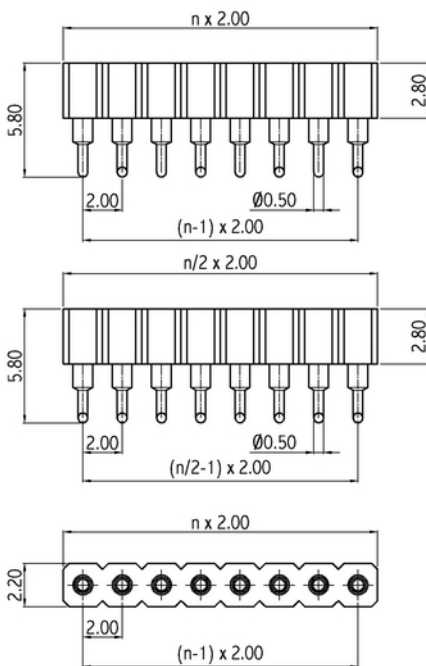
Technische Daten / Technical Data

| | |
|-----------------------|---|
| Isolierkörper | Thermoplastischer Kunststoff, nach UL94 V-0 |
| Insulator | Thermoplastic, rated UL94 V-0 |
| Kontaktmaterial | Hülse: Messing gedreht Feder: 4-Lamellen-Clip, Beryllium-Kupfer |
| Contact Material | Sleeve: screw machined brass Clip: 4-Finger-Clip, Beryllium-Copper |
| Kontaktoberfläche | Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) |
| Contact Surface | Acc. to options (see below), over Ni (1.3 ... 2.5µm) |
| Lötbarkeit | IEC 60512-12A |
| Solderability | IEC 60512-12A |
| Durchgangswiderstand | < 10mΩ |
| Contact Resistance | < 10mΩ |
| Isolationswiderstand | > 1000MΩ |
| Insulation Resistance | > 1000MΩ |
| Spannungsfestigkeit | 1kV _{RMS} |
| Test Voltage | 1kV _{RMS} |
| Nennspannung | 100V _{RMS} / 150V _{DC} |
| Voltage Rating | 100V _{RMS} / 150V _{DC} |
| Nennstrom | 3A |
| Current Rating | 3A |
| Temperaturbereich | -55°C ... +125°C |
| Temperature Range | -55°C ... +125°C |
| Verarbeitung | Reflow-Lötverfahren |
| Processing | Reflow soldering |



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Einsetzbar für Rundstifte Ø0,40-0,56mm.
Accept Ø0.40-0.56mm round pins.



| Series | Contacts* | Type* | Sleeve Plating | Clip Plating* | Packaging* |
|-------------|---|---|--|--|--------------------|
| 7452 | 010 | 3 | 50 | 00 | PPST |
| | 003-050 Einreihig Single row 004-100 Zweireihig Double row | 1 Einreihig B1, stehend Single row B1, vertical 2 Einreihig B2, stehend Single row B2, vertical 3 Zweireihig, stehend Double row, vertical 4 Einreihig, liegend Single row, horizontal | 50 Hülse verzinkt Tin plated sleeve | 00 Feder vergoldet Gold plated clip 10 Feder 0,25µm Gold 0.25µm gold plated clip 30 Feder 0,75µm Gold 0.75µm gold plated clip | ST PPST PPTR |

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pad / In tubes w/o Pick&Place-Pad
PPST In Stangen mit P&P-Pad / In tubes with P&P-Pad
PPTR Tape & Reel mit P&P-Pad / Tape & Reel with P&P-Pad

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** - please replace by your specifications.

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Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|--------------|
| Temperatur Minimum T_{Smin} | 150°C |
| Temperatur Maximum T_{Smax} | 200°C |
| Dauer $T_{Smin} - T_{Smax}$ | 60-180s |
| Temperatur Lötbereich T_L | 217°C |
| Verweildauer oberhalb T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Höchsttemperatur T_P | 260°C ±5 |
| Dauer Höchsttemperatur | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Dauer 25°C - Höchsttemperatur T_P | Max. 8 min |

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|--------------|
| Minimum Temperature T_{Smin} | 150°C |
| Maximum Temperatur T_{Smax} | 200°C |
| Duration $T_{Smin} - T_{Smax}$ | 60-180s |
| Soldering Range Temperature T_L | 217°C |
| Duration above T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Peak Temperature T_P | 260°C ±5 |
| Duration Peak Temperature | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Duration 25°C - Peak Temp. T_P | Max. 8min |

